



# Best Technical Methods for Unified Extensible Firmware Interface (UEFI) Development

**Reducing Platform Boot Times**

**Michael A. Rothman,  
Intel**

**Firmware Debugging: UEFI  
and USB for Platform  
Forensics**

**Brian Richardson,  
AMI**

**EFIS003**

Sponsors of Tomorrow: intel

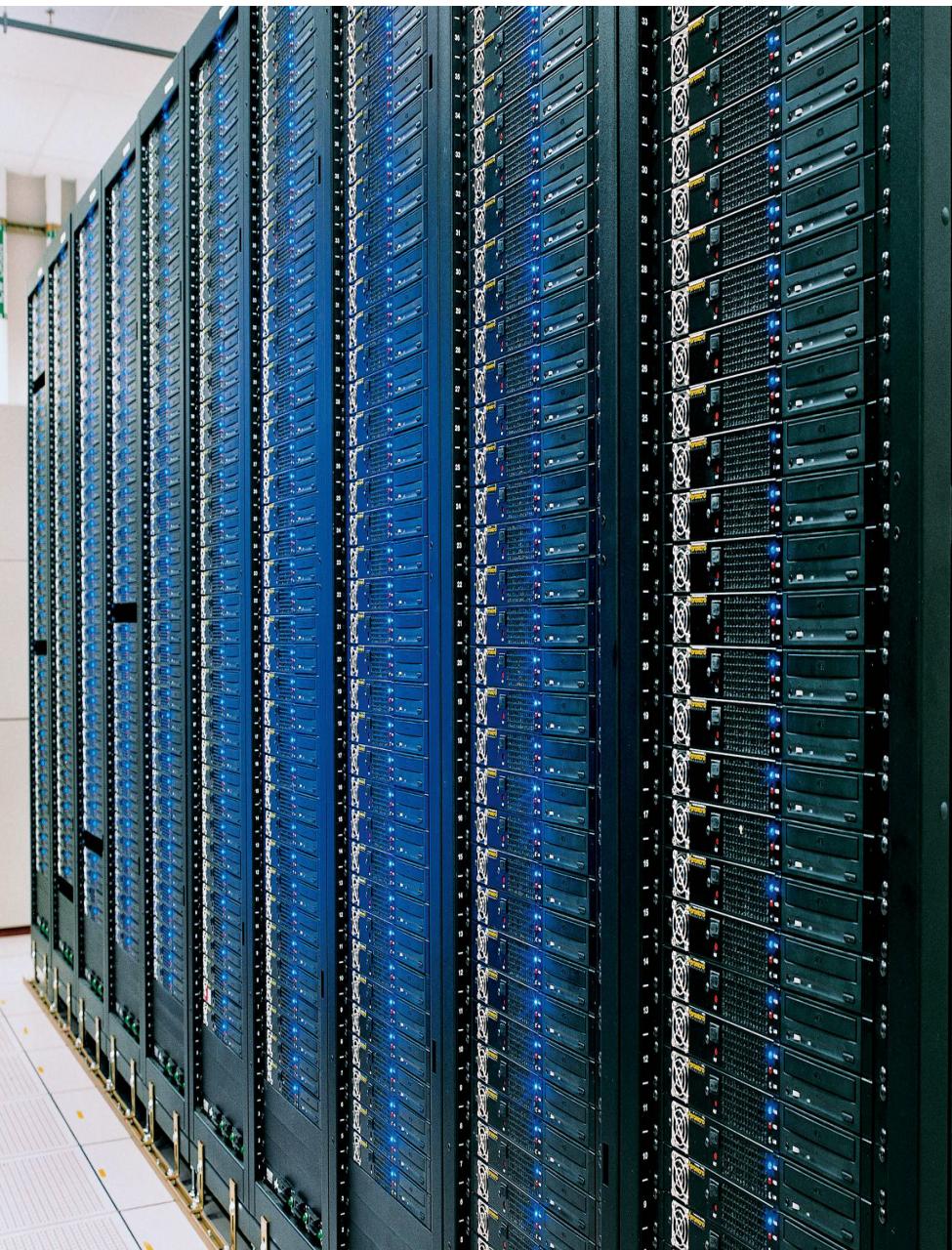


# Reducing Platform Boot Times

**Michael A. Rothman**  
Senior Staff Software Engineer

**EFIS003**

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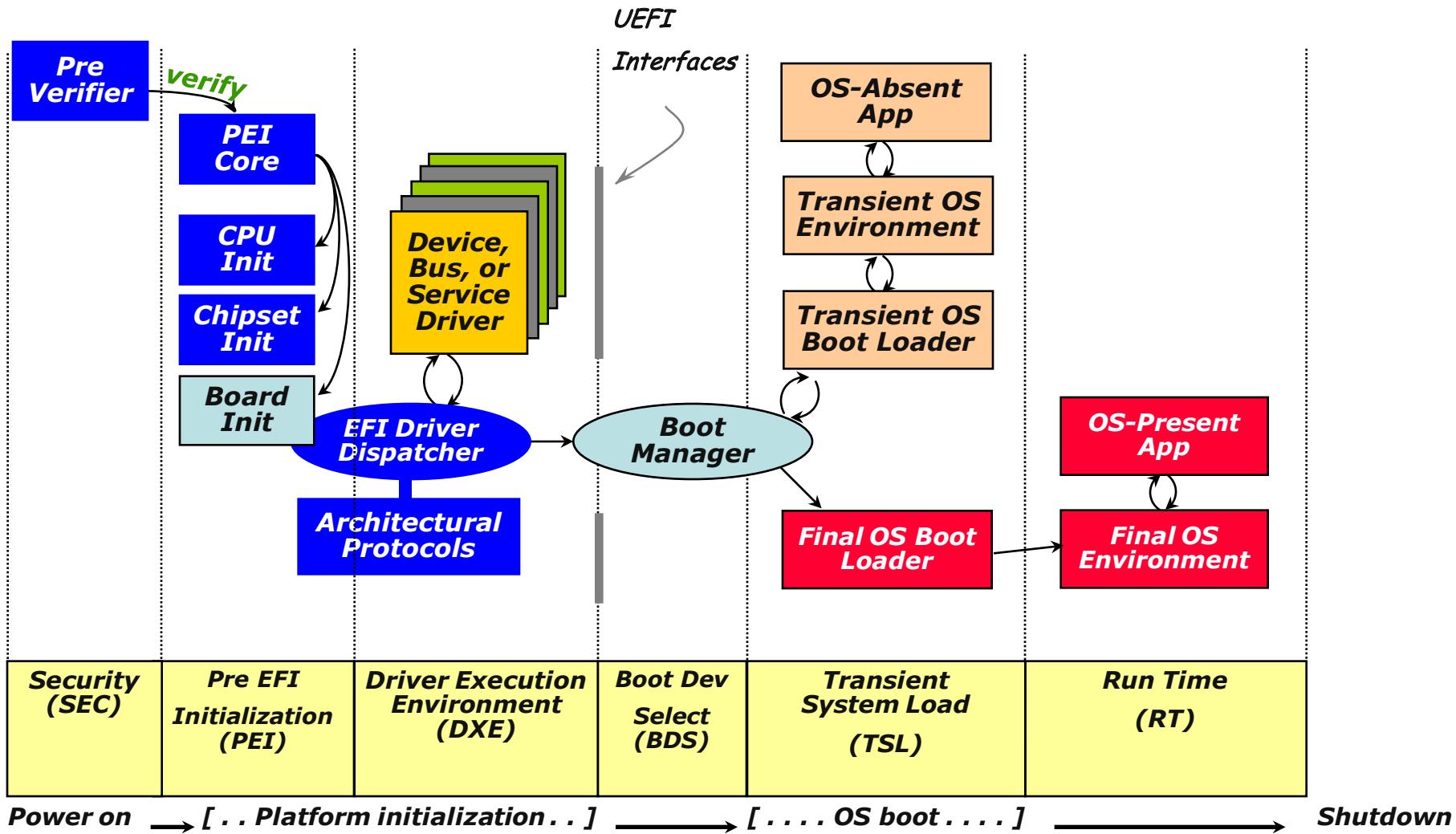
# Background Information

Factors in performance

Things to note

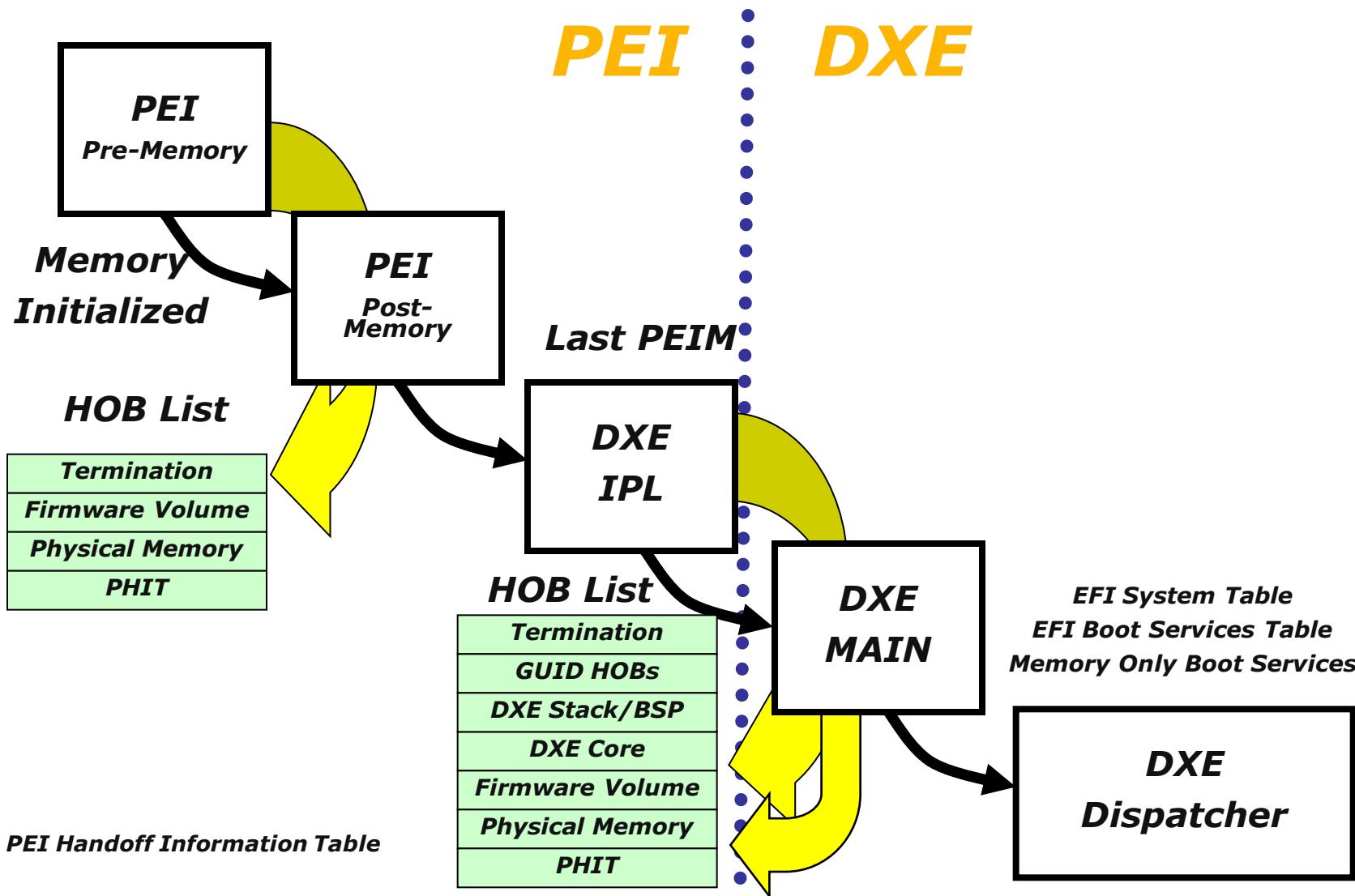
Key Learnings

# UEFI Phase Transitions



\*

# PEI to DXE Transition

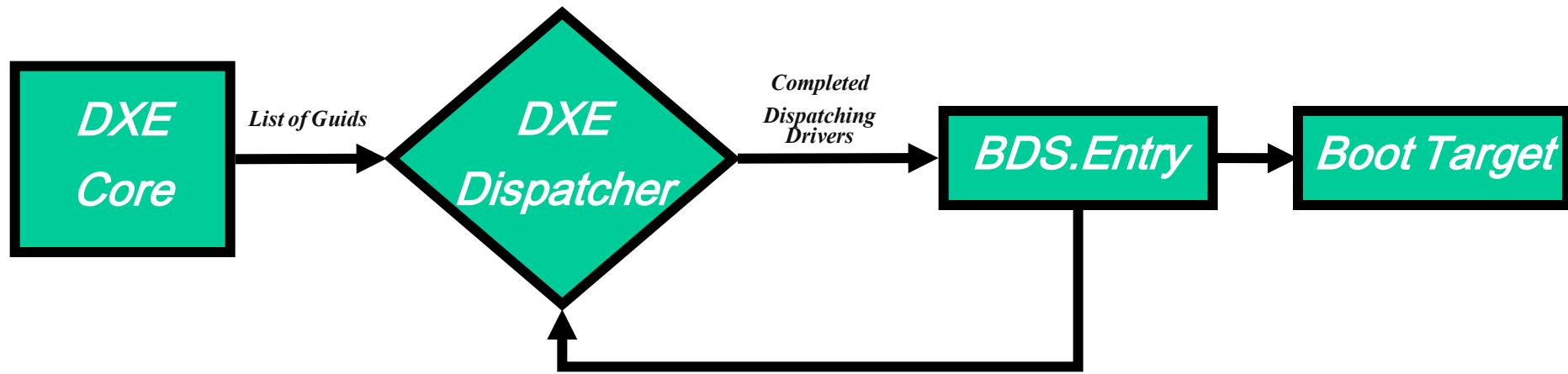


PHIT – PEI Handoff Information Table

\*

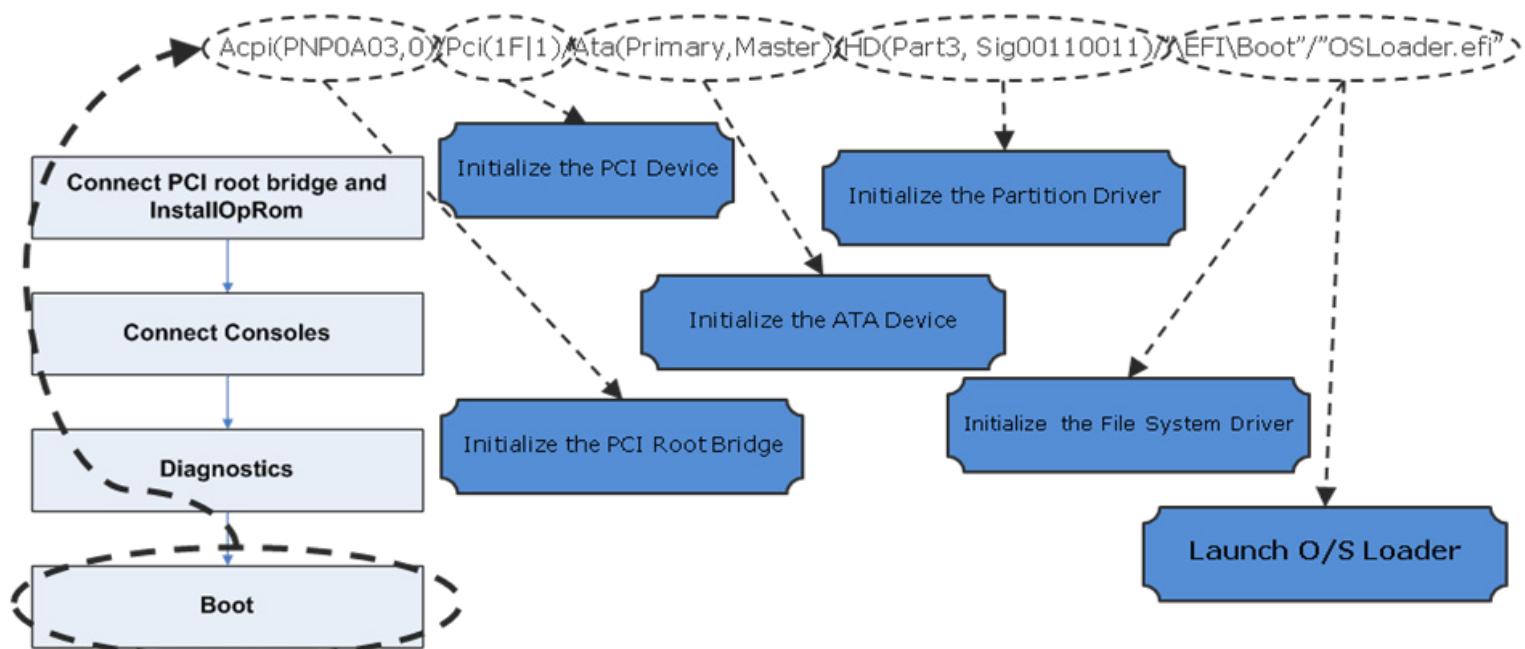
# Boot Device Selection

- Invoked after DXE Dispatcher is Complete
- Implemented as a driver
- Connects EFI drivers as required
  - Establishes Consoles (Keyboard, Video)
  - Processes EFI Boot Options (Boots O/S)

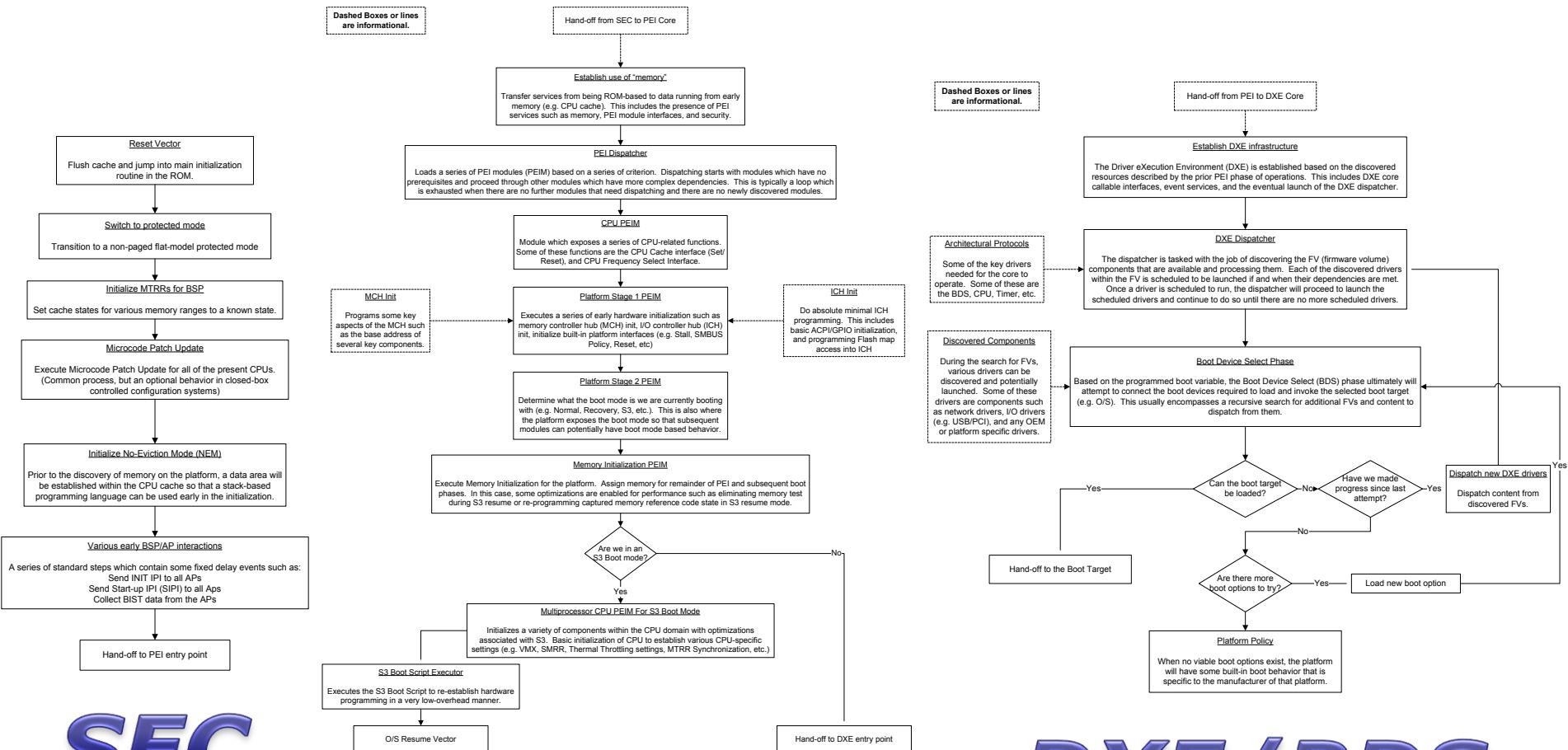


# What is a Boot Target?

- A boot target is described through an EFI Device Path.
  - A binary description of the physical location of a particular target.



# For those who want more detail.....

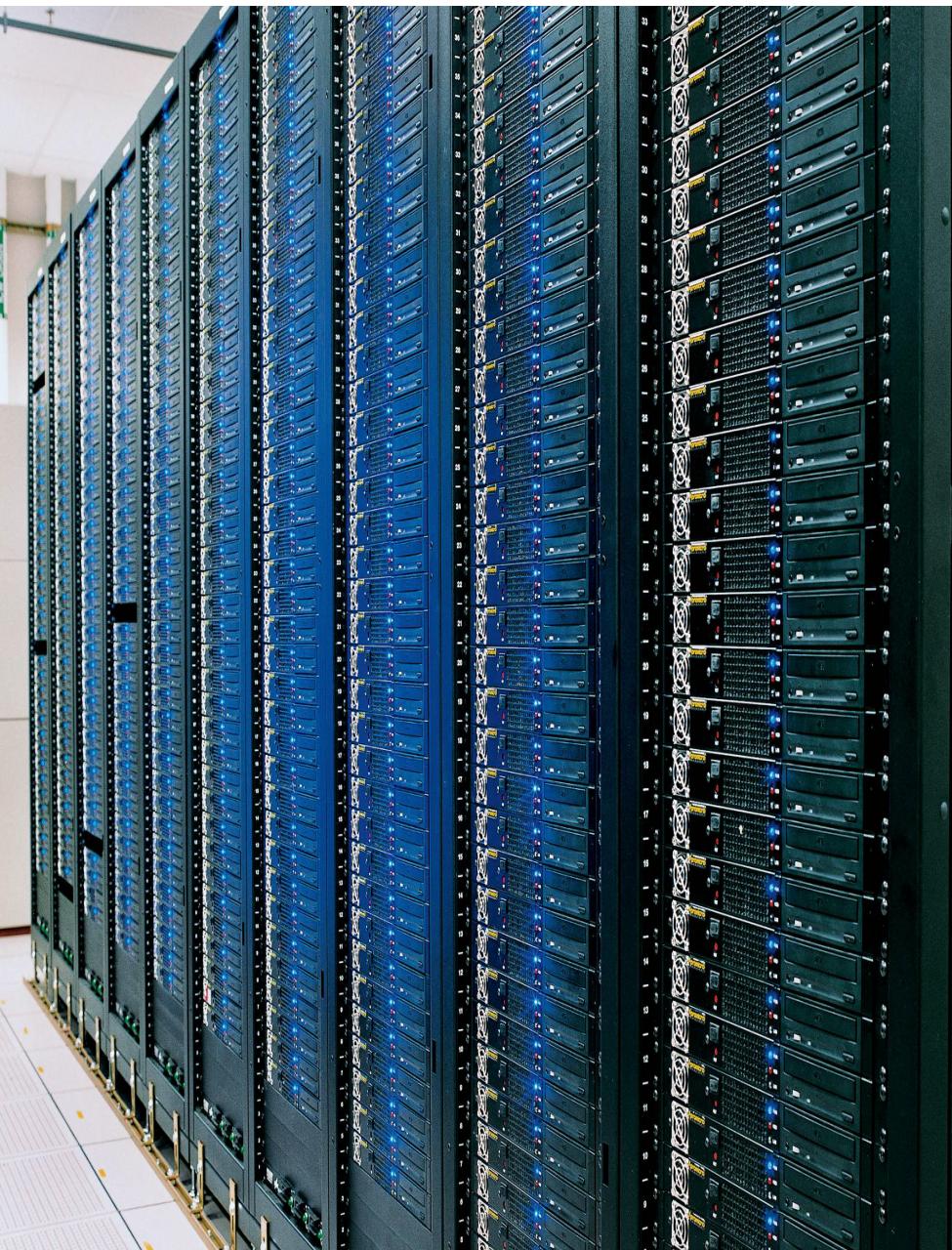


**SEC**

**PEI**

**DXE/BDS**

More details in a whitepaper located at: <http://edc.intel.com/Link.aspx?id=2355>



Background  
Information

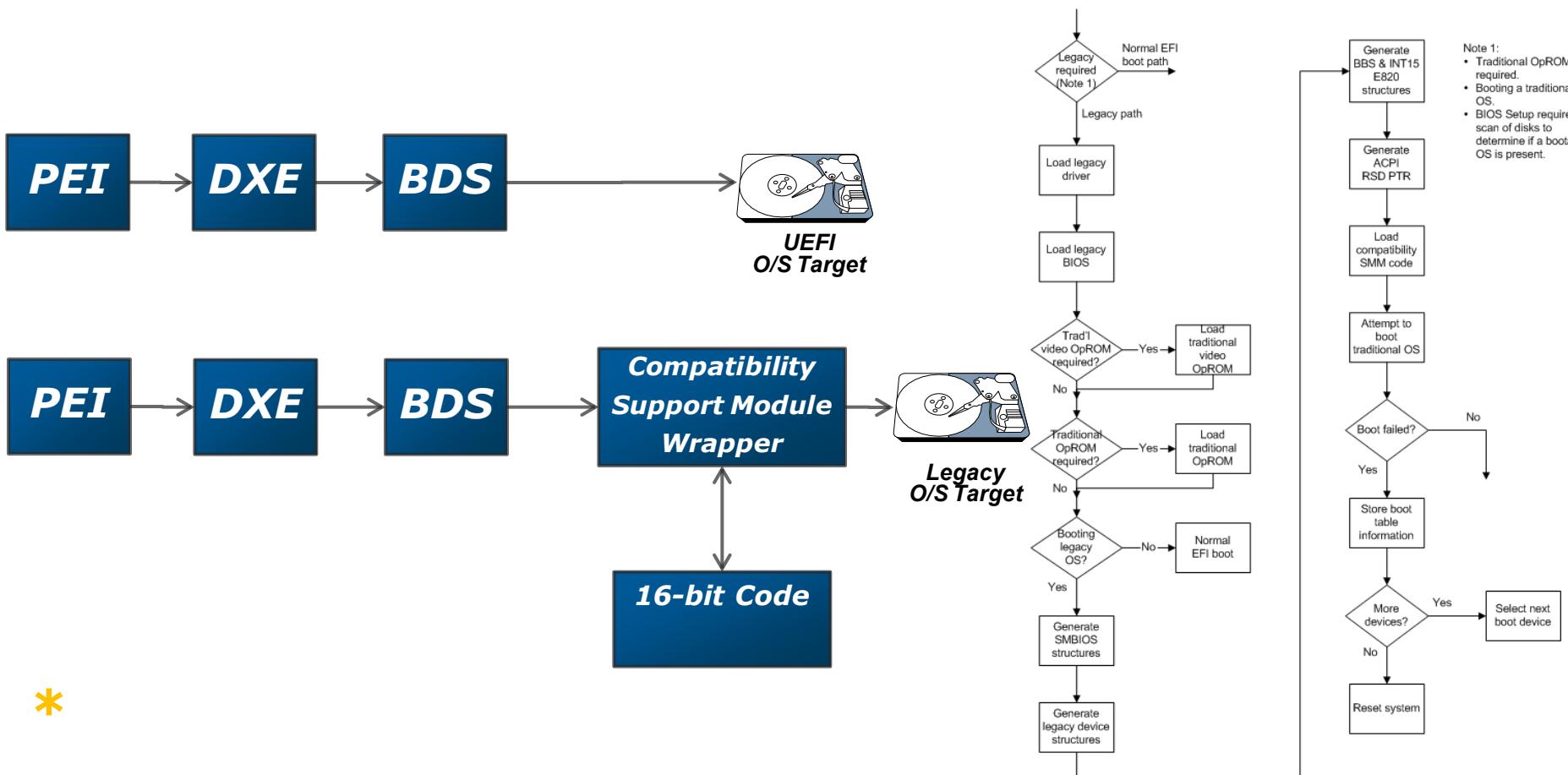
**Factors in  
performance**

Things to note

Key Learnings

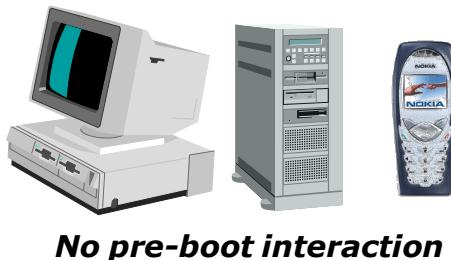
# O/S Target and Attributes

- What are the target Operating Systems?
  - Legacy Boot Support Required?
  - What data does the O/S require from the BIOS?
    - Some tables may not be required for certain targets.



# Platform Specific Expectations/Behavior

- What are the platform policies?
  - Expect to interact with user during the pre-boot?



- What type of hardware are we required to initialize prior to launching the O/S?



***Platform Policy choices affect boot times***

# Peripherals Affect Performance

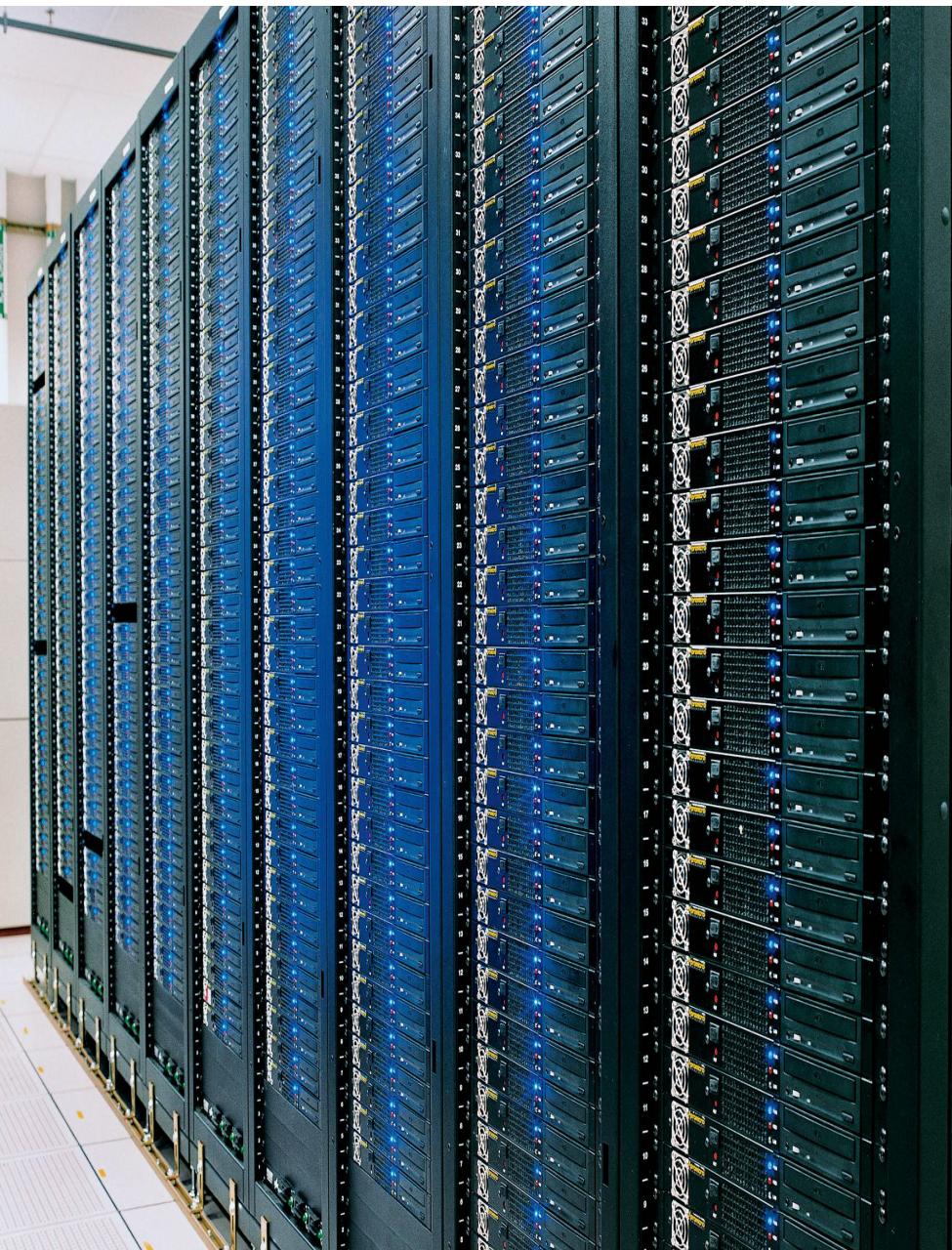
- Can we avoid slow hardware?
  - Use of an SSD boot device in lieu of rotating media can save seconds in the boot time.



Values	DRAM	SSD (34nm)	EIDE
Read Latency	~30 ns	65 <b>μs</b>	8.5 <b>ms</b>
Read BW (MB/s)	1800	250	120
Write Latency	~30 ns	85 <b>μs</b>	10 <b>ms</b>
Write BW (MB/s)	1800	70	120
Spin-up/down time	N/A	N/A	<b>1-2s++</b>



***Boot hardware can affect times tremendously***



Background  
Information

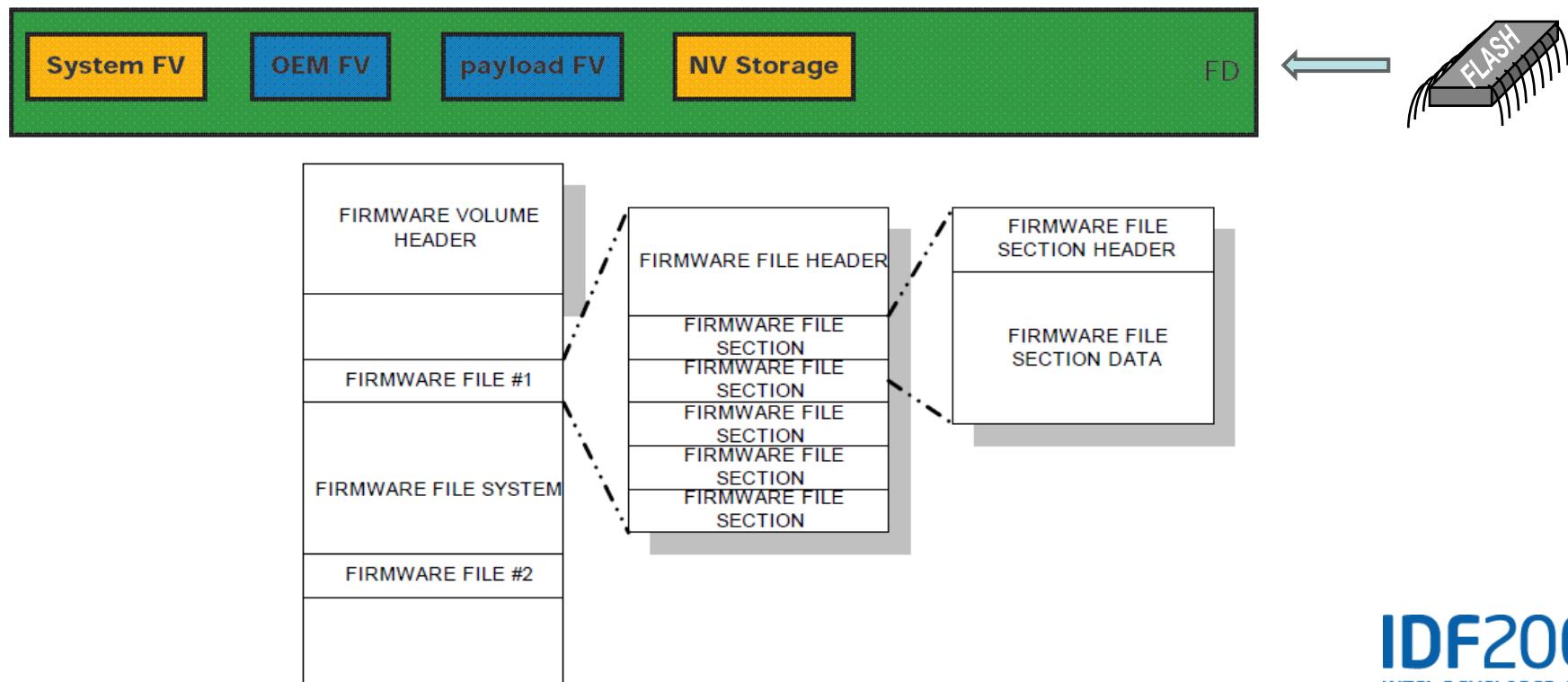
Factors in  
performance

Things to note

Key Learnings

# Size and Organization matters!

- The less you have to read from FLASH the better.
  - It is possible to organize the FLASH layout so that you never search firmware volumes which contain nothing of interest for that configuration.



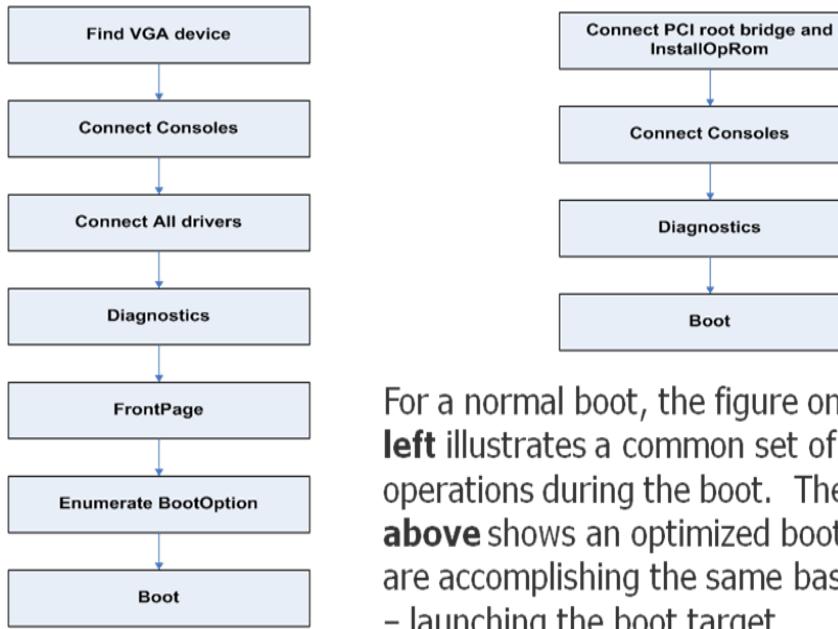
# Where to Optimize?

- Try to avoid slowing down the boot process for to accommodate the case which almost never happens.
  - Pausing for a keystroke in the anticipation that someone might interrupt the boot process.
  - Initializing and reading from alternate recovery devices when in almost all cases, we aren't going to be asked to recover the platform.

***Platform behavior requirements often dictate where certain optimizations can occur.***

# Functional Optimization

- Note that depending on platform needs, we may very well do different things....

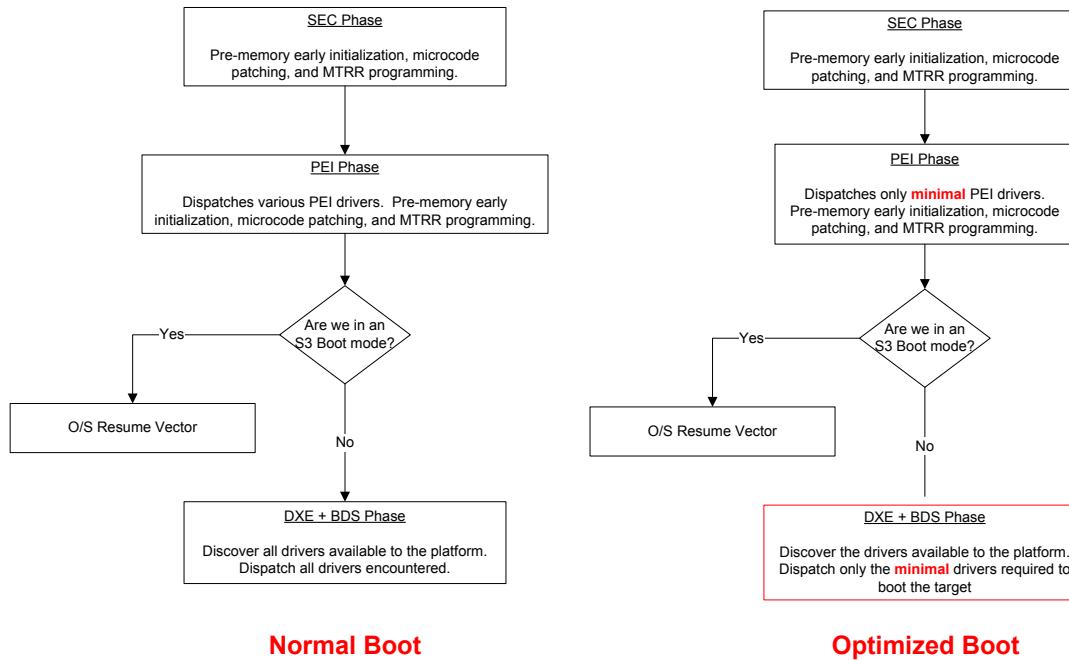


For a normal boot, the figure on the **left** illustrates a common set of operations during the boot. The figure **above** shows an optimized boot. Both are accomplishing the same basic goal – launching the boot target

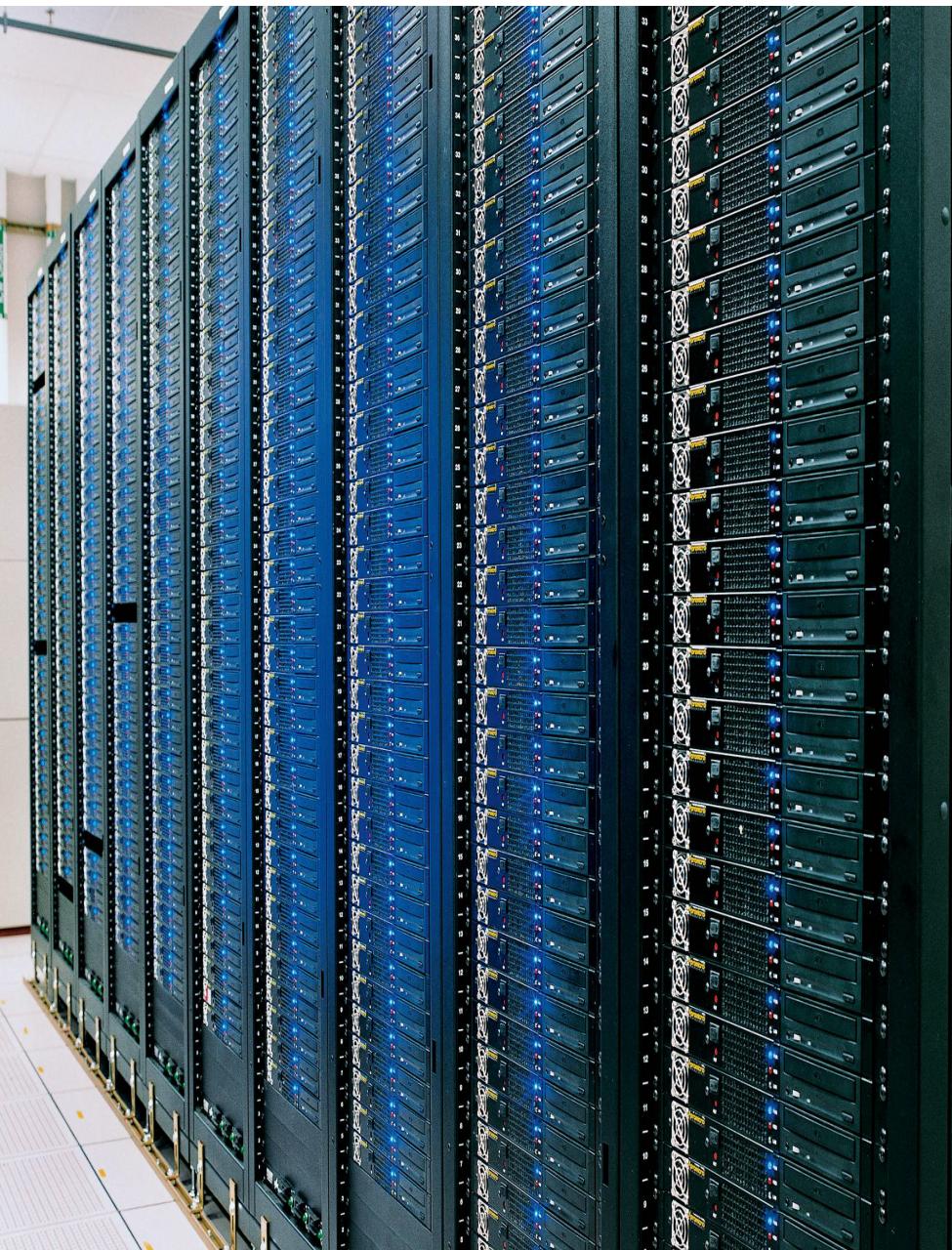
***BIOS functionality can and will vary***

# Maintain Architectural Design

- Performance Optimization doesn't mean we lose UEFI compatibility



***Optimize without losing UEFI compatibility***



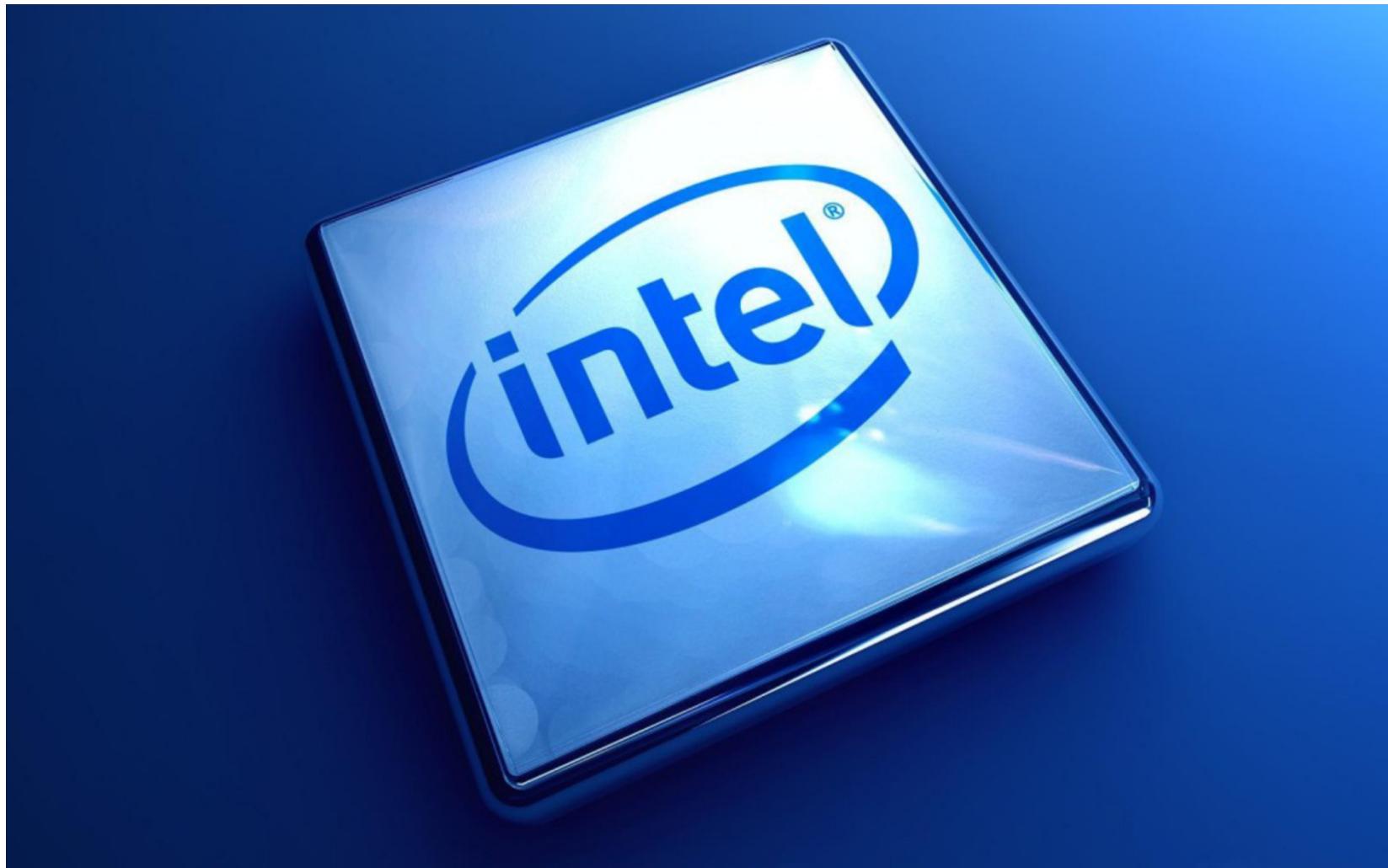
**Background  
Information**

**Factors in  
performance**

**Things to note**

**Key Learnings**

# Demo Video



SEC	Phase Duration :	26342 (us)
PEI	Phase Duration :	1230905 (us)
DXE	Phase Duration :	998234 (us)
BDS	Phase Duration :	7396050 (us)
Total	Duration :	<b>9.651531 (s)</b>

**Normal Boot**

SEC	Phase Duration :	26419 (us)
PEI	Phase Duration :	763315 (us)
DXE	Phase Duration :	443021 (us)
BDS	Phase Duration :	766778 (us)
Total	Duration :	<b>1.999533 (s)</b>

**Optimized Boot**

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# Key Learnings

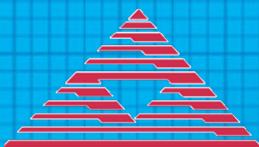
- Performance can be greatly affected by Platform Policy and Hardware Configurations
  - Firmware engineers get involved early in the platform design
- BIOS Design Elements Can Improve Performance
  - A variety of software optimization techniques exist within the BIOS
- Performance Optimization does not mean a lack of compatibility
- See the published whitepaper for more details:  
<http://edc.intel.com/Link.aspx?id=2355>





# Firmware Debugging: UEFI and USB for Platform Forensics

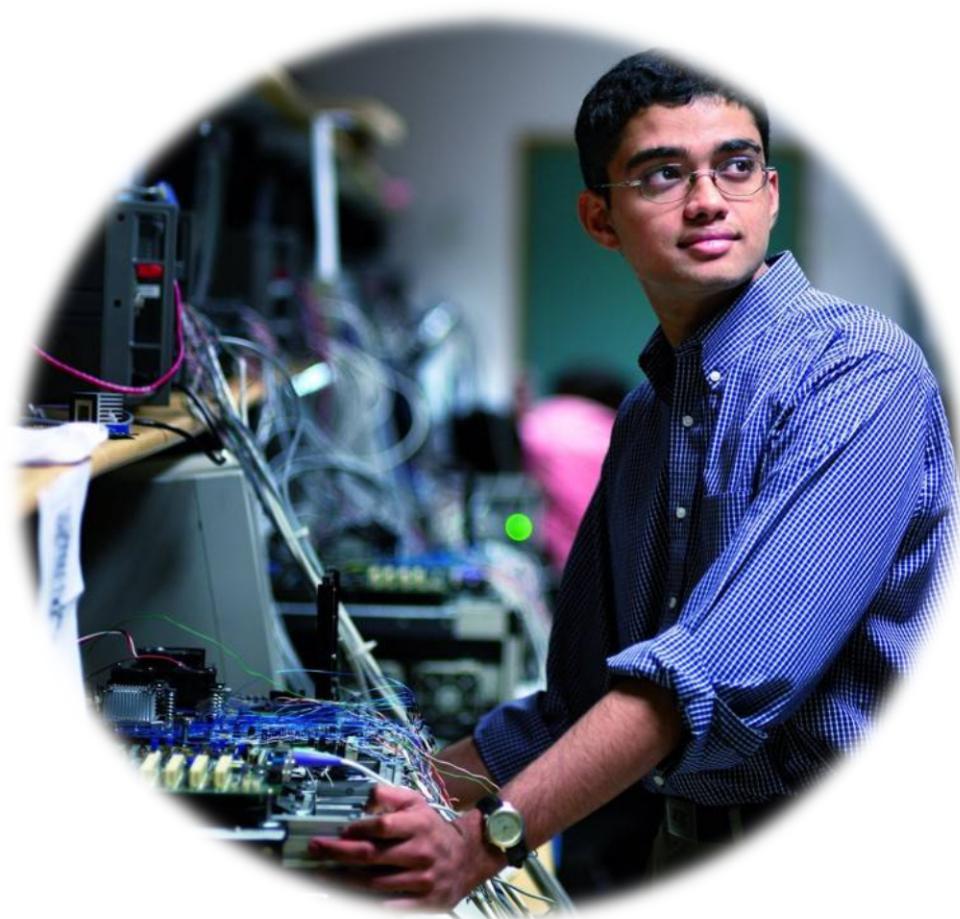
**Brian Richardson - American Megatrends, Inc.  
Senior Technical Marketing Engineer**



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Sponsors of Tomorrow: intel

# Agenda



**Limitations for UEFI  
Debugging**

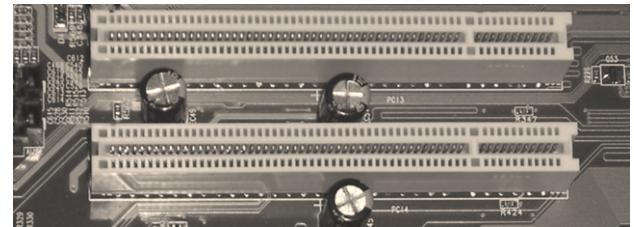
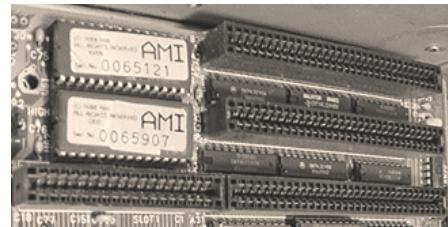
**Utilizing USB Debug  
Solutions**

**Extending UEFI  
Debugging Concepts**

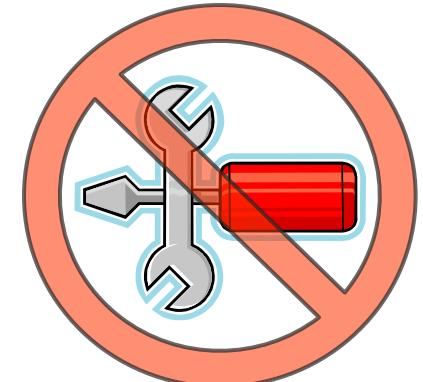
**Using USB Debugging  
in the Field**

# Limitations for UEFI Debugging

- Moving to UEFI introduced new debug tools
  - Debug Strings, Status Codes, C-style debugging
  - Problem: these tools are for developers, not users
- Tools from “the BIOS days” are disappearing



- “No user-serviceable parts inside”
  - Thin & light systems
  - Netbook, nettop, embedded
  - No expansion slots



# Firmware Debug Tool Wishlist

*Common ground between developers & field technicians*

## The Developer

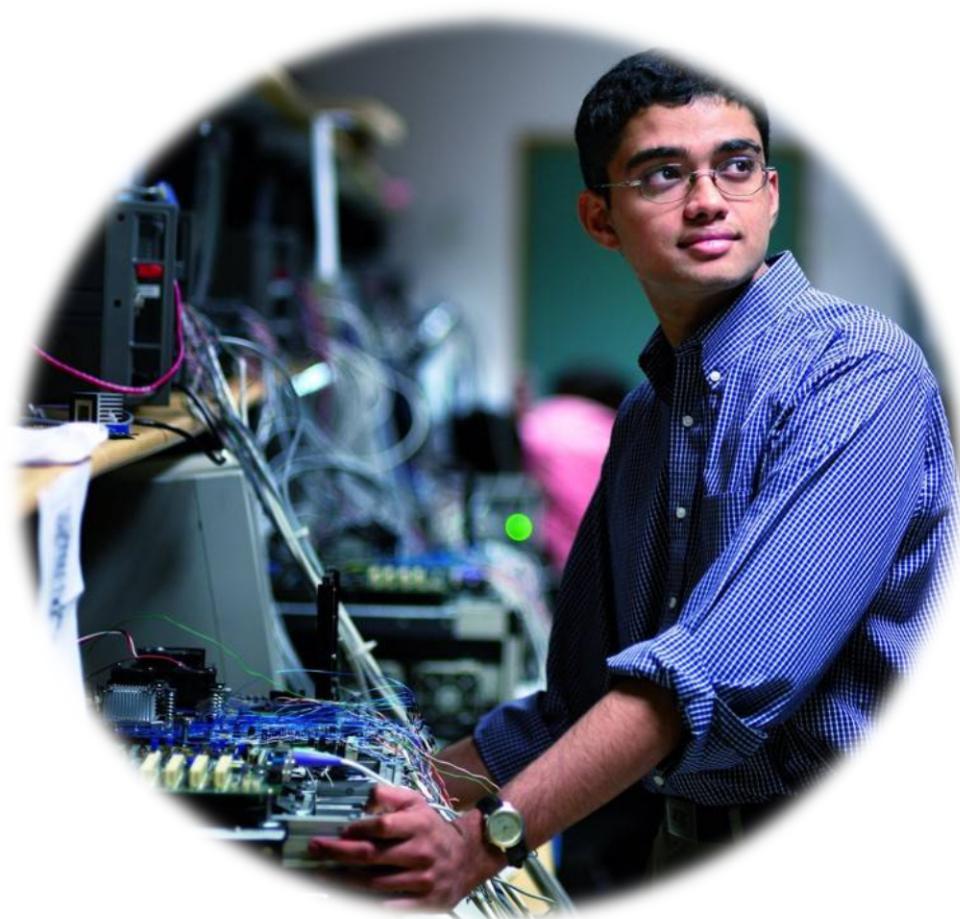
- Use standalone or with another PC
- Use w/o opening case
- View checkpoints
- Store data for analysis
- Use on production HW
- View debug strings
- Source-level debug

## The Field Technician

- Use standalone or with another PC
- Use w/o opening case
- View checkpoints
- Store data for analysis
- Use on production HW
- No proprietary ports

**New Platform Designs Demand New Debug Tools**

# Agenda



**Limitations for UEFI  
Debugging**

**Utilizing USB Debug  
Solutions**

**Extending UEFI  
Debugging Concepts**

**Using USB Debugging  
in the Field**

# Utilizing USB Debug Solutions

## Why USB?

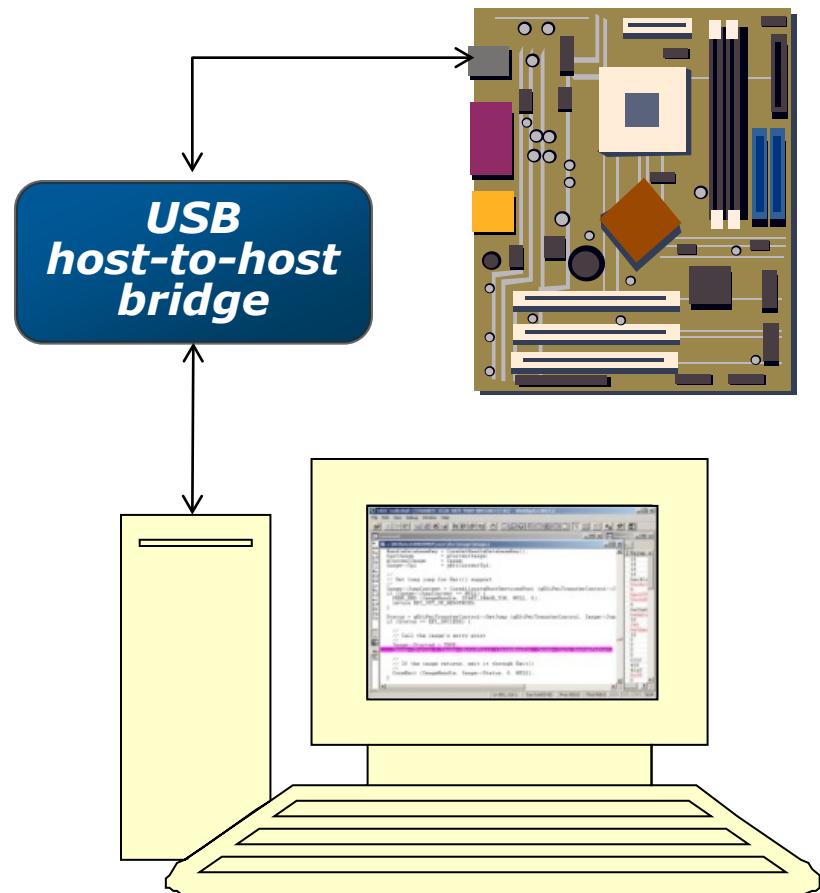
- USB is Ubiquitous
- Externally Accessible, Screwdriver Free
- USB 2.0 Enables Early Debugging via the EHCI debug port
- Same port works with debug devices or standard USB devices

## What's a "debug port"

- One USB port supporting a simplified USB protocol
  - Fast protocol
  - Does not require full memory stack
  - Works only with "debug descriptor" device
- Supported by Intel ICH/SCH with USB 2.0

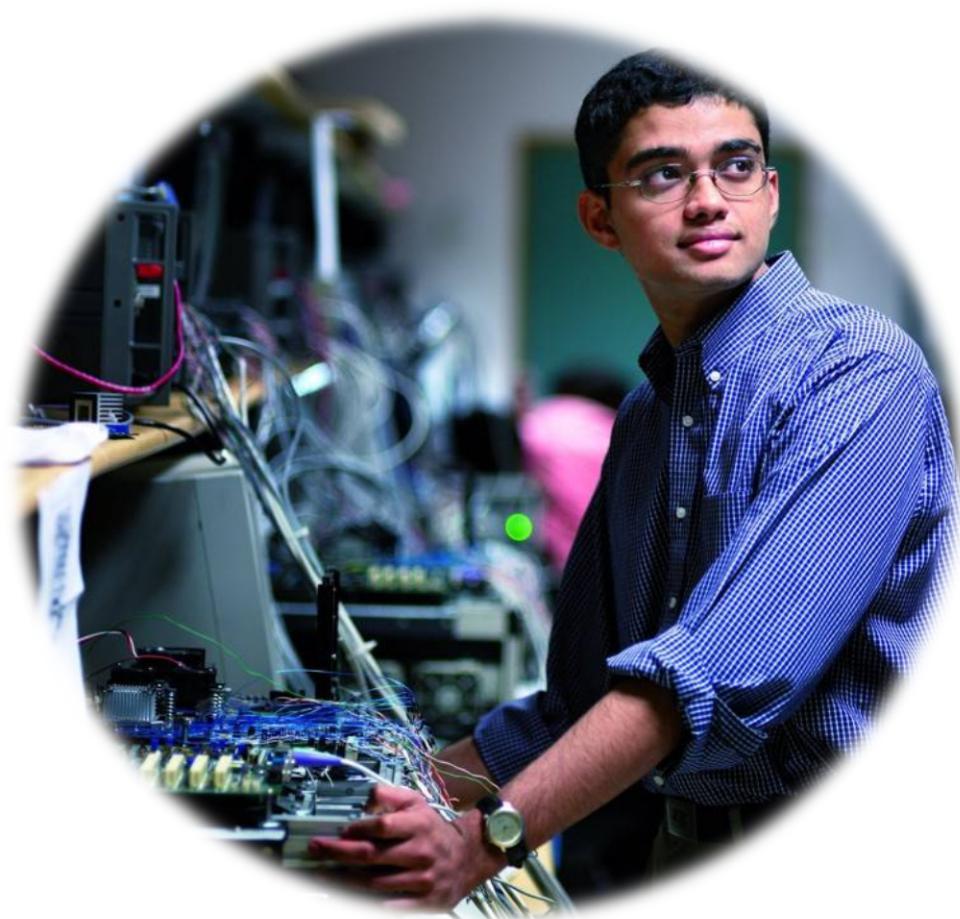
# Today's Uses in Source Debugging

- USB Debug Port works as a “transport layer”
  - UEFI Debug Protocol
  - Requires host-to-host bridge
- Shown previously at IDF
- Example: AMI Debug
  - Source-level debug
  - DXE, PEI and UEFI Shell
  - Add breakpoints
  - Read & write mem/IO/PCI
  - Redirect debug messages
  - Redirect remote console



***USB Debug Port Is Already Available & Used by IBVs***

# Agenda



**Limitations for UEFI  
Debugging**

**Utilizing USB Debug  
Solutions**

**Extending UEFI  
Debugging Concepts**

**Using USB Debugging  
in the Field**

# Extending UEFI Debugging Concepts



## Field Technicians

- Diagnose systems using checkpoints or status codes.
- Translate “hexadecimal nerd nonsense” into usable data.



## Quality Assurance

- Measure boot performance using checkpoint timing
- Record data for test reports
- Easily pinpoint hangs



## BIOS/UEFI Developers

- Read checkpoints
- Optimize boot performance using checkpoint timing
- Enable source-level debug

# Extending UEFI Debugging Concepts



## Field Technicians

For years, the focus has been on fixing problems for *BIOS developers*



## Quality Assurance

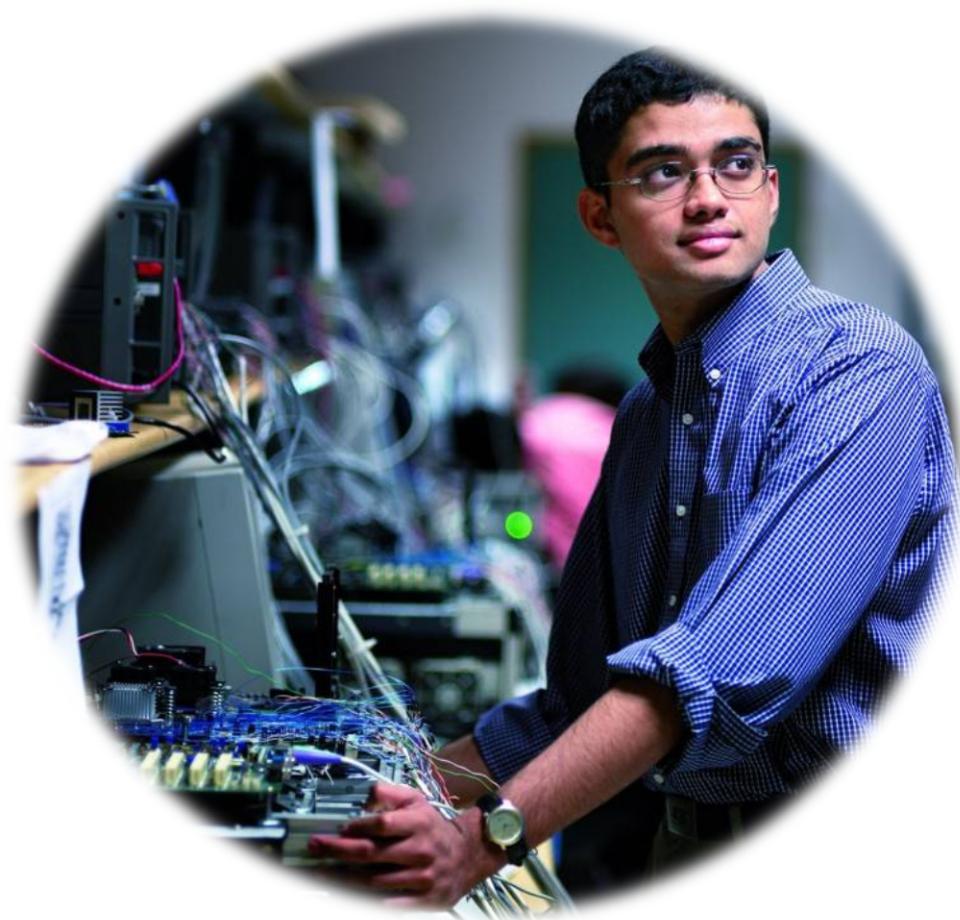
There are *new product opportunities* solving the same set of problems for QA & field technicians



## BIOS/UEFI Developers

**New Tools in UEFI  
Can Go Beyond  
Traditional BIOS  
Debugging**

# Agenda



**Limitations for UEFI  
Debugging**

**Utilizing USB Debug  
Solutions**

**Extending UEFI  
Debugging Concepts**

**Using USB Debugging  
in the Field**

# Using USB Debugging in the Field

*An Example Based on Today's Tools from AMI*

- Stand-Alone Operation
  - Read & store checkpoints
  - Store UEFI debug strings
  - Replace cryptic hex values with text descriptions
  - Measure boot timing
- Use with Another PC
  - Stream UEFI debug strings live to a console
  - Enable source-level debug
  - Access stored sessions
  - Enabled in firmware by drop-in modules

AMI**Debug**<sup>TM</sup> RX



**Connects to USB  
EHCI Debug Port**

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# Enhanced Features in USB Debug

- UEFI Debug Strings
  - Used when BIOS is compiled in “debug mode”
  - Pass strings in DEBUG() & ASSERT() macros
  - Better information than just checkpoints
  - Redirected to AMI Debug Rx & USB Debug Port

```
[AmiDbg]Register PPI Notify: f894643d-c449-42d1-8ea8-85bdd8c65bde
[AmiDbg]Register PPI Notify: 605ea650-c65c-42e1-ba80-91a52ab618c6
[AmiDbg]CpuPeiBeforeMem.Entry(FFFECB85)
[AmiDbg]NBPEI.Entry(FFFF495B)
[AmiDbg]SBPEI.Entry(FFFF1AED)
[AmiDbg]>>> PM Registers Before GPIO Init <<<
[AmiDbg]+===== PM Registers dump =====+
[AmiDbg]  PM1a_EVT_BLK.PM1_STS      : Addr = 0400 => Val = 0001
[AmiDbg]  PM1a_EVT_BLK.PM1_EN       : Addr = 0402 => Val = 0000
```

# Enhanced Features in USB Debug

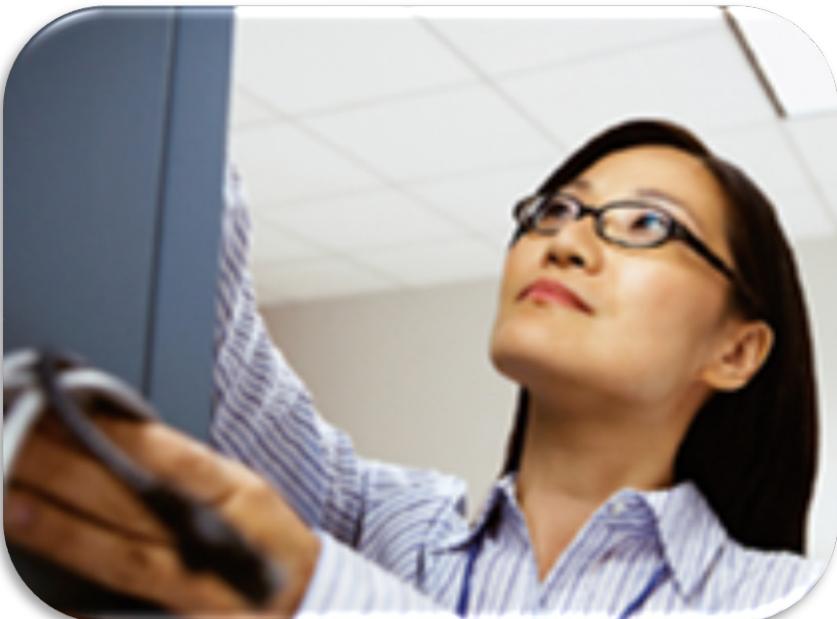
- Boot Time Analysis
  - Used on any BIOS with AMI Debug Rx support
  - Based on device's internal timer
  - Total boot time or time between checkpoints

Session Start Time	:	06/10/2009 15:16:44	
Total Checkpoints	:	52	
Duration of last boot	:	23,703ms	
BIOS Tag	:	0ABFL032	
BIOS Type	:	Aptio 4.x	
BIOS Build Time	:	05/11/2009 17:00:07	
Checkpoint Output			
Num	CP	Time (ms)	String
1	0x0011	1,372ms	PRE-MEM CPU INIT
2	0x0015	1,513ms	PRE-MEM NB INIT
3	0x0019	1,883ms	PRE-MEM SB INIT
4	0x002B	8,674ms	MEM INIT. SPD READ

# Demo

## AMI Debug Rx in use ...

- Capture Checkpoints
- Retrieve Stored Checkpoint Session
- Boot Time Analysis
- Store UEFI Debug Strings



# Problems Solved w/AMI Debug Rx

Works with any System Form Factor



- No PCI slot or LPC header
- Externally accessible
- Uses commodity USB port
- Utilizes existing technology in today's USB 2.0 EHCI controllers

Single Solution for Multiple Applications

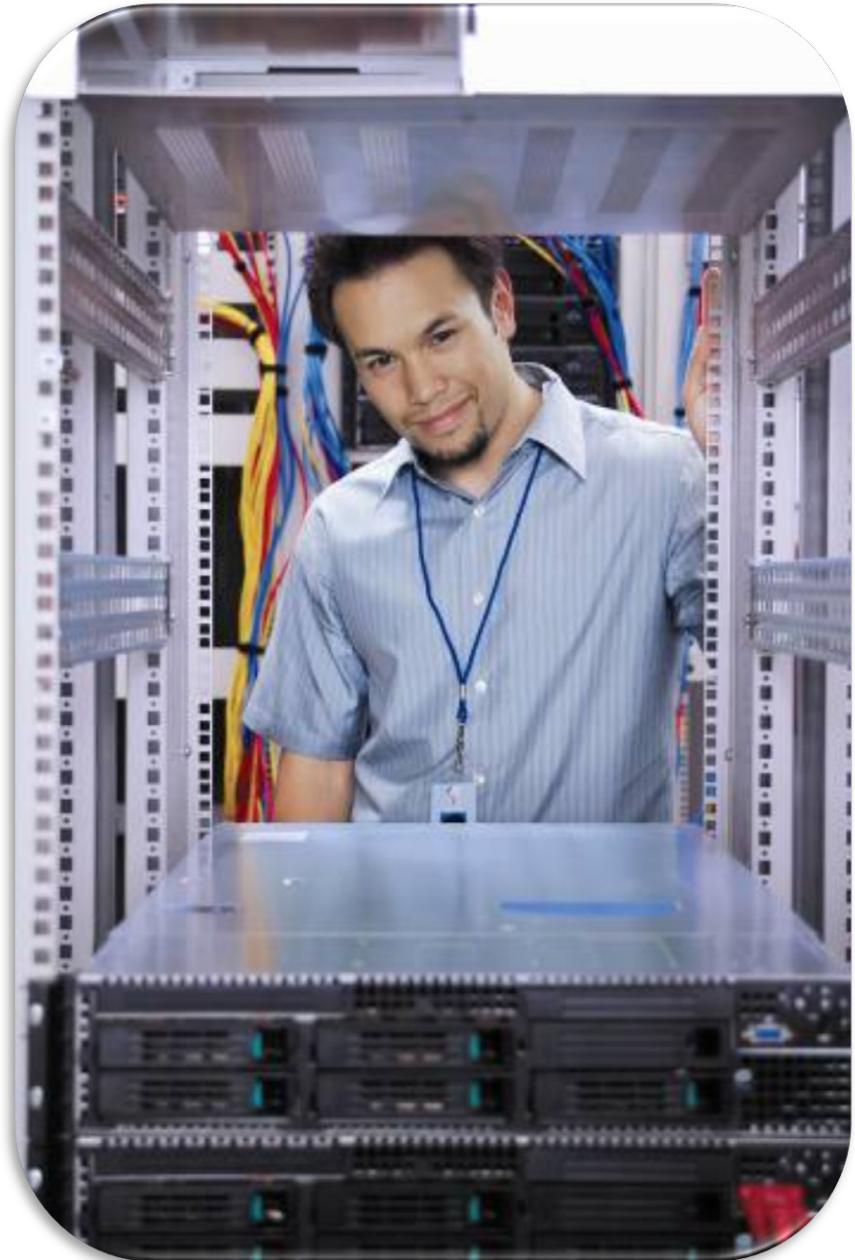


- Standalone or with another PC
- Field Debug & Quality Assurance
- Measure boot performance
- Enable source-level debugging

***IBV Debug Tools Can Support Products  
From Development to Deployment***

# Key Learnings

- New Platform Designs Demand New Debug Tools
- USB Debug Port Is Already Available & Used by IBVs
- New Tools in UEFI Can Go Beyond Traditional BIOS Debugging
- IBV Debug Tools Can Support Products From Development to Deployment



# **Next Steps – Best Technical Methods for UEFI Development**

- UEFI is a rich environment visit the UEFI web site**
  - Learning center on UEFI web site**
- Down load the white papers**
- Work with your IBVs for the latest innovation tools**

# Additional resources on UEFI:

- Demos in the Showcase
  - UEFI Booth #136
  - American Megatrends Inc #429
- Talk to other UEFI members in the showcase
- Other information on the web
  - Boot Optimization Whitepaper:  
<http://edc.intel.com/Link.aspx?id=2355>
  - “[Improving BIOS Debugging Using USB 2.0 Methods](#)” Whitepaper available at [www.ami.com](http://www.ami.com)
  - AMI Debug Rx product information at [www.ami.com/amidebugrx](http://www.ami.com/amidebugrx)
  - “[USB2 Debug Device Functional Specification, Revision 0.90](#)” available at [www.intel.com](http://www.intel.com)
  - Specifications and Implementation sites: [www.tianocore.org](http://www.tianocore.org), [www.uefi.org](http://www.uefi.org), [www.intel.com/technology/efi](http://www.intel.com/technology/efi)
- Technical book from Intel Press:
  - “Beyond BIOS: Implementing the Unified Extensible Firmware Interface with Intel’s Framework” [www.intel.com/intelpress](http://www.intel.com/intelpress)

# IDF 2009 UEFI Sessions

EFI#	Company	Description	Time	RM	D
P001	Dell, HP, IBM, Intel, Microsoft	Using UEFI as the Foundation for Innovation	10:15	2005	T
S001	IBM, Intel	Intel Advanced Technology in the Enterprise: Best Security Practices	16:15	2001	W
S002	Dell, Intel, Insyde SW	Secure FW Lockdown through Standardized UEFI Management Protocols	17:15	2001	W
S003	Intel, AMI	Best Technical Methods for UEFI Development -Reducing Platform Boot Times -Firmware Debugging: UEFI and USB for platform forensics	11:10	2002	Th
S004	Microsoft, Insyde SW, Intel	UEFI Boot Time Opt. Under Microsoft Windows 7	13:40	2002	Th
S005	Phoenix, Intel	Transitioning the Plug-In Industry from Legacy to UEFI: Real World Cases	14:40	2002	Th
Q001	Intel, All	UEFI Q & A session	15:40	2002	Th

✓ **DONE**

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# Q&A

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